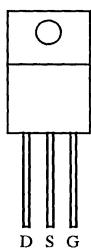


N-Channel Enhancement-Mode Transistor

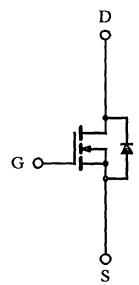
Product Summary

$V_{(BR)DSS}$ (V)	$r_{DS(on)}$ (Ω)	I_D (A)
400	0.30	15

TO-254AA
Hermetic Package

Case Isolated

Top View

Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	400	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ($T_J = 150^\circ\text{C}$)	I_D	15	A
		9.5	
Pulsed Drain Current	I_{DM}	60	
Maximum Power Dissipation	P_D	150	W
		60	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 150	$^\circ\text{C}$
Lead Temperature ($1/16''$ from case for 10 sec.)	T_L	300	

Thermal Resistance Ratings

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient	R_{thJA}	50	0.83	$^\circ\text{C/W}$
Maximum Junction-to-Case	R_{thJC}			
Case-to-Sink	R_{thCS}	0.2		

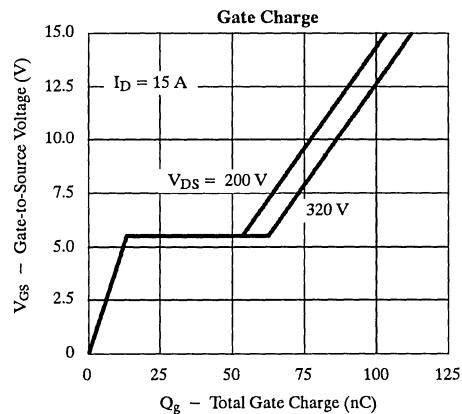
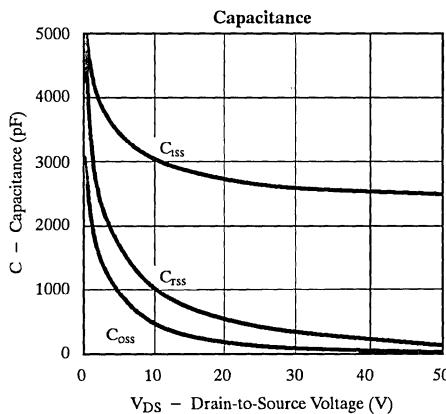
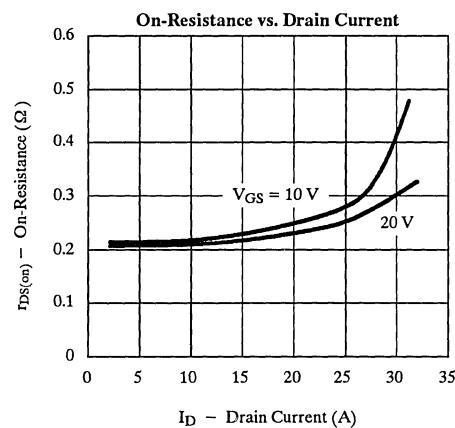
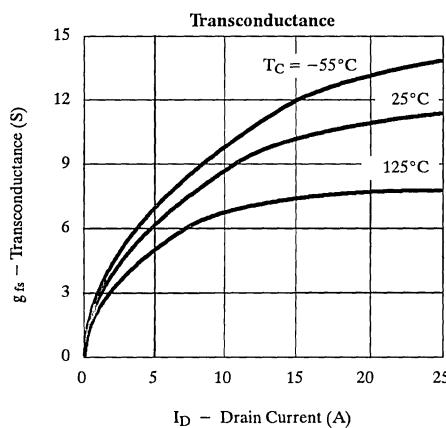
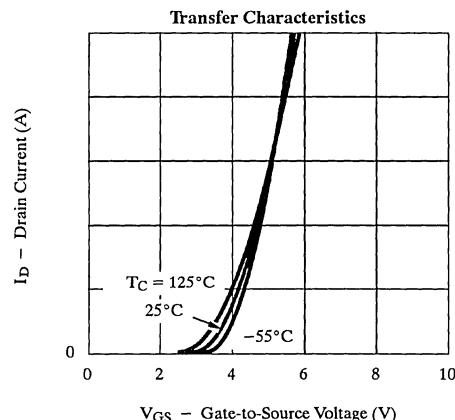
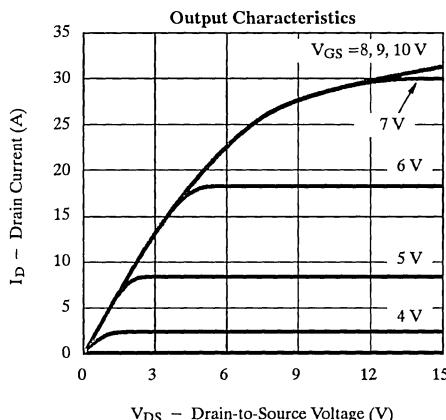
Specifications ($T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Limit			Unit
			Min	Typ ^a	Max	
Static						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0 \text{ V}, I_D = 250 \mu\text{A}$	400			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250 \mu\text{A}$	2.0		4.0	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0 \text{ V}, V_{\text{GS}} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 320 \text{ V}, V_{\text{GS}} = 0 \text{ V}$			25	
		$V_{\text{DS}} = 320 \text{ V}, V_{\text{GS}} = 0 \text{ V}, T_J = 125^\circ\text{C}$			250	μA
On-State Drain Current ^b	$I_{\text{D}(\text{on})}$	$V_{\text{DS}} = 10 \text{ V}, V_{\text{GS}} = 10 \text{ V}$	15.0			A
Drain-Source On-State Resistance ^b	$r_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10 \text{ V}, I_D = 9.5 \text{ A}$		0.023	0.30	
		$V_{\text{GS}} = 10 \text{ V}, I_D = 9.5 \text{ A}, T_J = 125^\circ\text{C}$		0.4	0.66	Ω
Forward Transconductance ^b	g_{fs}	$V_{\text{DS}} = 15 \text{ V}, I_D = 9.5 \text{ A}$		8.5	24	S
Dynamic						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0 \text{ V}, V_{\text{DS}} = 25 \text{ V}, f = 1 \text{ MHz}$		2700		
Output Capacitance	C_{oss}			450		
Reverse Transfer Capacitance	C_{rss}			160		pF
Total Gate Charge ^c	Q_g	$V_{\text{DS}} = 200 \text{ V}, V_{\text{GS}} = 10 \text{ V}, I_D = 15 \text{ A}$		77	110	
Gate-Source Charge ^c	Q_{gs}			14	18	nC
Gate-Drain Charge ^c	Q_{gd}			39	65	
Turn-On Delay Time ^c	$t_{\text{d}(\text{on})}$			14	35	
Rise Time ^c	t_r	$V_{\text{DD}} = 200 \text{ V}, R_L = 13 \Omega$ $I_D \approx 15 \text{ A}, V_{\text{GEN}} = 10 \text{ V}, R_G = 2.4 \Omega$		30	60	
Turn-Off Delay Time ^c	$t_{\text{d}(\text{off})}$			54	150	ns
Fall Time ^c	t_f			15	75	
Source-Drain Diode Ratings and Characteristics						
Continuous Current	I_S				15	
Pulsed Current	I_{SM}				60	A
Diode Forward Voltage ^b	V_{SD}	$I_F = 15 \text{ A}, V_{\text{GS}} = 0 \text{ V}$	0.85		1.7	V
Reverse Recovery Time	t_{rr}	$I_F = 15 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$		350	800	ns
Reverse Recovery Charge	Q_{rr}			2.0		μC

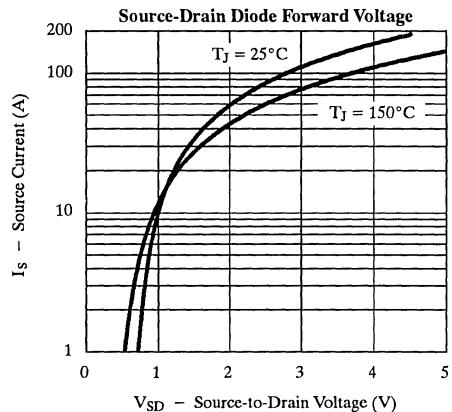
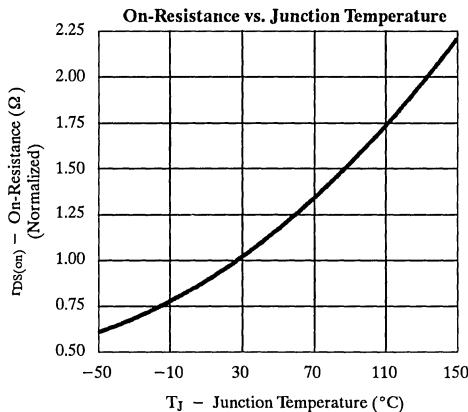
Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
- c. Independent of operating temperature.

Typical Characteristics (25°C Unless Otherwise Noted)



Typical Characteristics (25°C Unless Otherwise Noted)



Thermal Ratings

